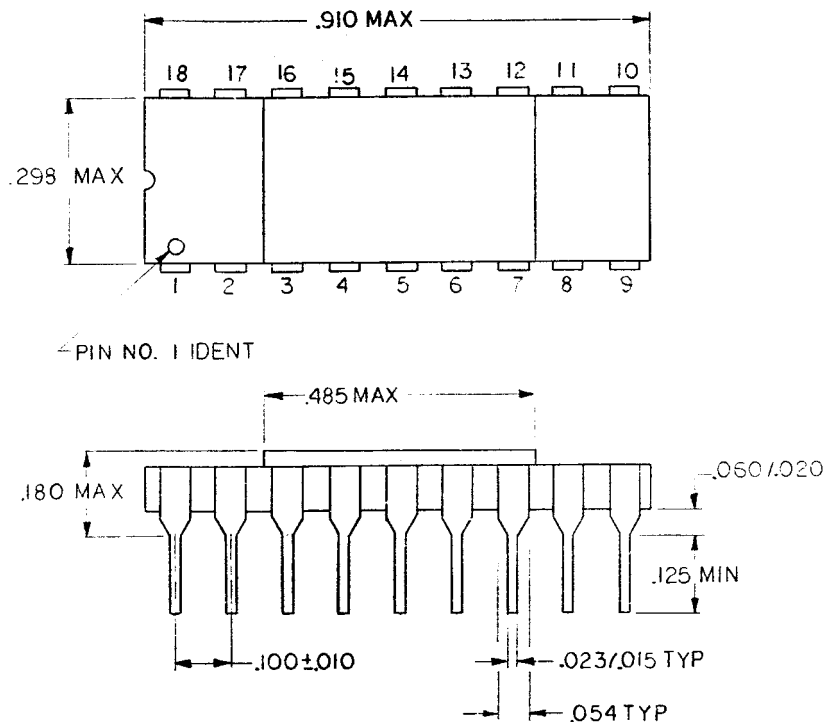


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REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
E	DIM WAS .165 MAX/IS .180 MAX DWG NO WAS: D18A REDRAW	01767	7-17-84	OC/ P. H. H.



2. THE LEAD FINISH, NICKEL UNDERPLATE AND BASE METAL SHALL CONFORM TO THE REQUIREMENTS OF MIL-M-38510E.
1. LEAD FINISH TO BE ONE OF THE FOLLOWING:
 - 1.1 200 MICROINCHES MINIMUM SOLDER MEASURED AT THE CREST OF MAJOR FLATS.
 - 1.2 200-800 MICROINCHES TIN PLATE OVER 50-350 MICROINCHES NICKEL UNDERPLATE OR BASE METAL.
 - 1.3 50-100 MICROINCHES GOLD OVER 50-350 MICROINCHES NICKEL UNDERPLATE.

NOTES: unless otherwise specified

MIL-M-38510
CONFIGURATION CONTROL

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. TOLERANCES ARE:		APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION 2900 Semiconductor Drive, Santa Clara, Calif. 95051	
DECIMALS:	ANGLES:	DRN	7-17-84		
.XX ±		DET. CHK.	7-19-84		
.XXX ±	N/A	ENGR. CHK.	7-24-84		
.XXXX ±		APPROVAL		18 LEAD HERMETIC DIP (D)	
MATERIAL	N/A	PROJECTION		SCALE	SIZE
FINISH	SEE NOTES			5 X 1	C
DO NOT SCALE DRAWING				FORMERLY: D18A	DRAWING NUMBER: MKT-D18A
				SHEET 1	OF 1